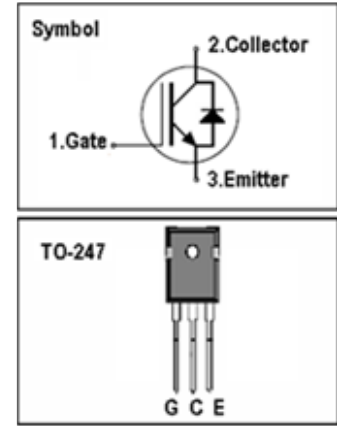


## IGBT

### Features

- 650V,40A
- $V_{CE(sat)(typ.)}=1.65V@V_{GE}=15V,I_C=40A$
- High speed switching
- Positive temperature coefficient
- Reliable and Rugged
- Low  $V_{CE(sat)}$



### General Description

JIAEN Trench IGBTs reduces the conduction loss, improves switching performance and enhances the avalanche energy. Used in motor drives, solar inverter, Resonant converters, and other soft switching applications.

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$V_{CES}$	Collector-Emitter Voltage	650	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 30$	V
$I_C$	Continuous Collector Current ( $T_C=25^\circ C$ )	80	A
	Continuous Collector Current ( $T_C=100^\circ C$ )	40	A
$I_{CM}$	Pulsed Collector Current (Note 1)	120	A
$I_F$	Diode Continuous Forward Current ( $T_C=100^\circ C$ )	40	A
$I_{FM}$	Diode Maximum Forward Current (Note 1)	120	A
$t_{sc}$	Short Circuit Withstand Time	8	us
$P_D$	Maximum Power Dissipation ( $T_C=25^\circ C$ )	227	W
	Maximum Power Dissipation ( $T_C=100^\circ C$ )	113	W
$T_J$	Operating Junction Temperature Range	-55 to +175	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to +175	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{th\ j-c}$	Thermal Resistance, Junction to case for IGBT	0.66	$^\circ C/W$
$R_{th\ j-c}$	Thermal Resistance, Junction to case for Diode	0.58	$^\circ C/W$
$R_{th\ j-a}$	Thermal Resistance, Junction to Ambient	40	$^\circ C/W$

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise noted )

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=250\mu A$	650	-	-	V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{CE}=650V, V_{GE}=0V$	-	-	100	$\mu A$
$I_{GES}$	Gate Leakage Current, Forward	$V_{GE}=\pm 20V, V_{CE}=0V$	-	-	$\pm 200$	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=1mA$	4.3	-	6.3	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=40A$	-	1.65	1.95	V
$Q_g$	Total Gate Charge	$V_{CC}=520V$ $V_{GE}=15V$ $I_C=40A$	-	146		nC
$Q_{ge}$	Gate-Emitter Charge		-	24		nC
$Q_{gc}$	Gate-Collector Charge		-	71		nC
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=400V$ $V_{GE}=15V$ $I_C=40A$ $R_G=5\Omega$ Inductive Load $T_C=25^\circ\text{C}$	-	20	-	ns
$t_r$	Turn-on Rise Time		-	67	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	104	-	ns
$t_f$	Turn-off Fall Time		-	74	-	ns
$E_{on}$	Turn-on Switching Loss		-	0.95	-	mJ
$E_{off}$	Turn-off Switching Loss		-	0.93	-	mJ
$E_{ts}$	Total Switching Loss		-	1.88	-	mJ
$C_{ies}$	Input Capacitance	$V_{CE}=25V$	-	2540	-	pF
$C_{oes}$	Output Capacitance	$V_{GE}=0V$	-	126	-	pF
$C_{res}$	Reverse Transfer Capacitance	$f=1MHz$	-	67	-	pF

**Electrical Characteristics of Diode** ( $T_C=25^\circ\text{C}$  unless otherwise noted )

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_F$	Diode Forward Voltage	$I_F=40A$	-	1.65	3.2	V
$t_{rr}$	Diode Reverse Recovery Time	$V_{CE}=400V$	-	55		ns
$I_{rr}$	Diode peak Reverse Recovery Current	$I_F=40A$	-	5.9		A
$Q_{rr}$	Diode Reverse Recovery Charge	$di/dt=200A/\mu s$	-	0.11		$\mu C$

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature

## Typical Performance Characteristics

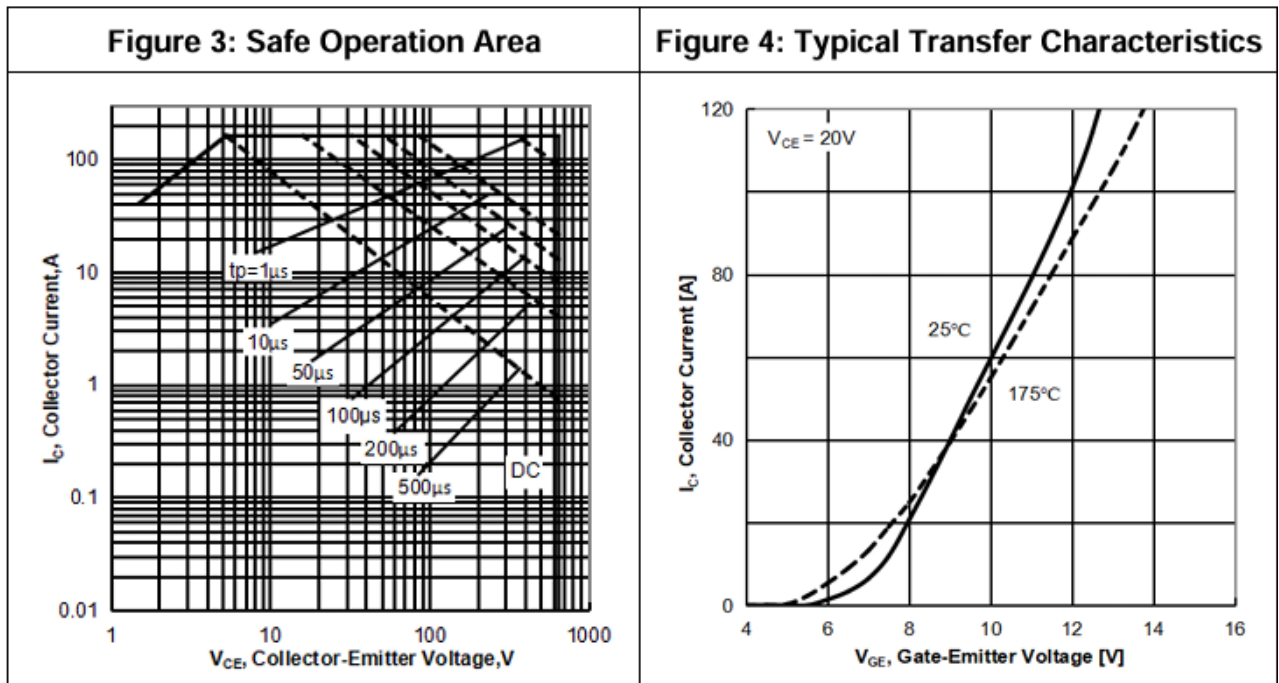
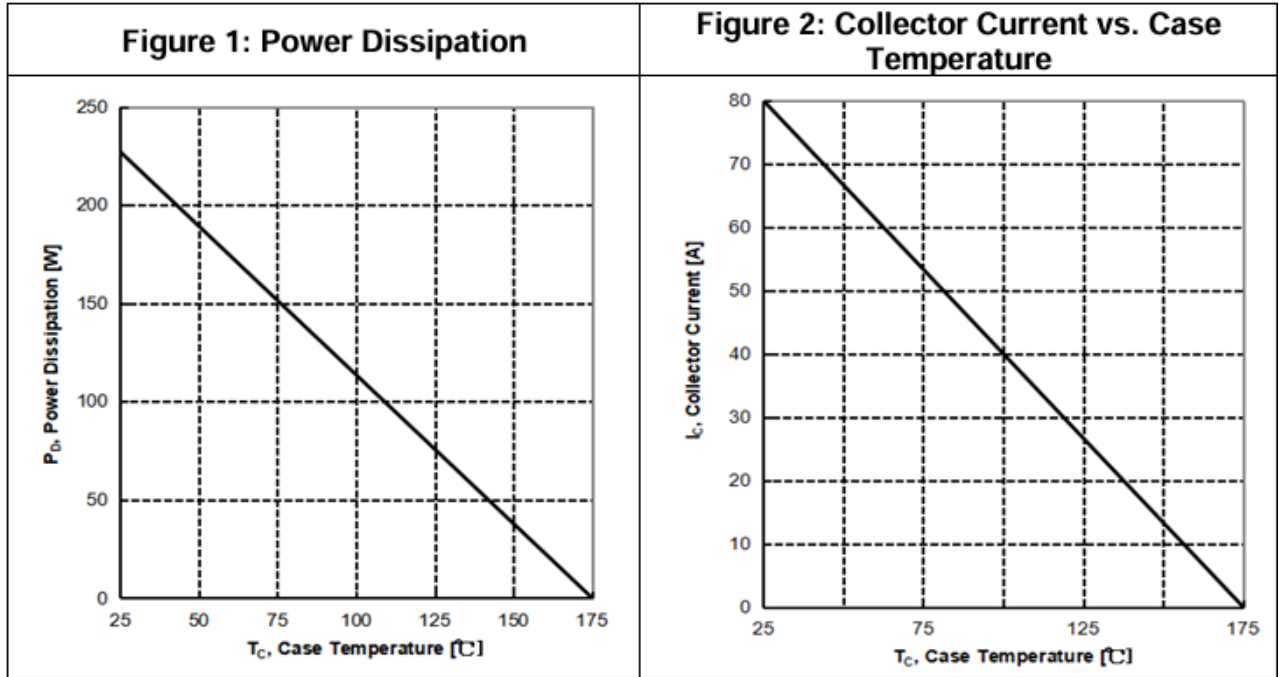


Figure 5: Typical Output Characteristics

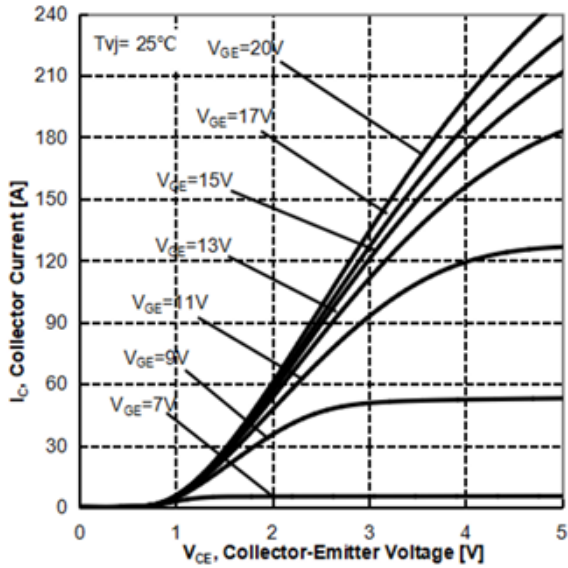


Figure 6: Typical Output Characteristics

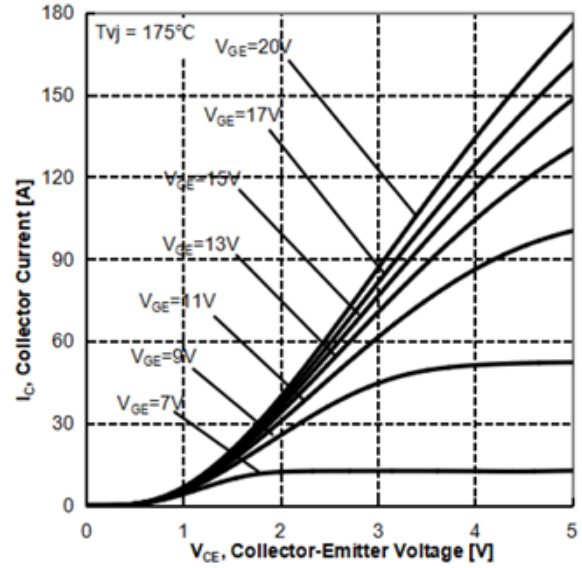


Figure 7: Typical Collector-Emitter Saturation Voltage vs. Junction Temperature

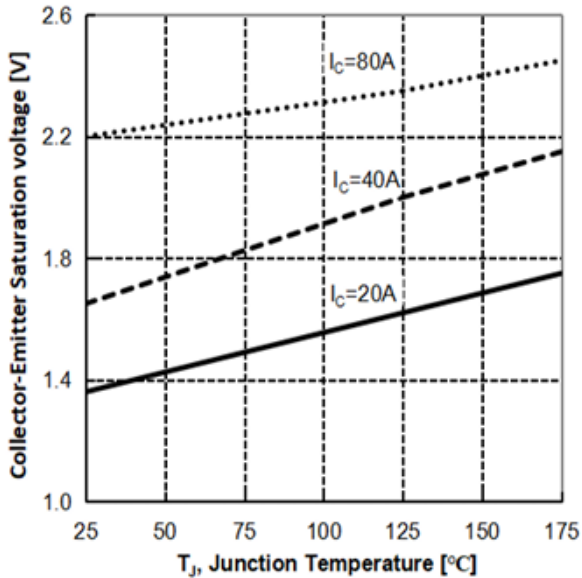
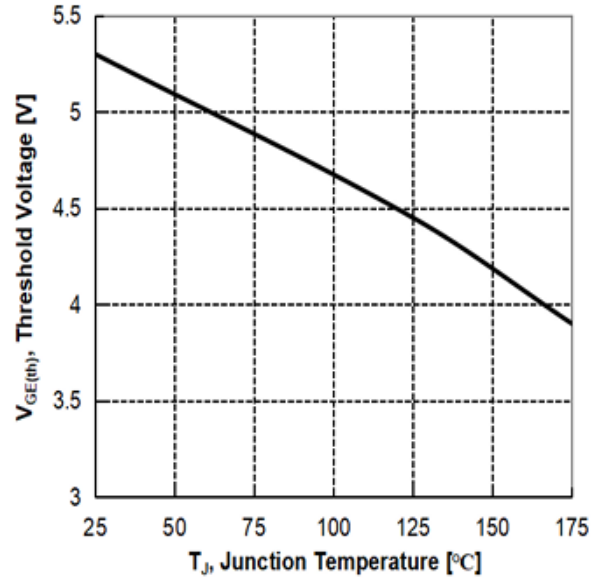
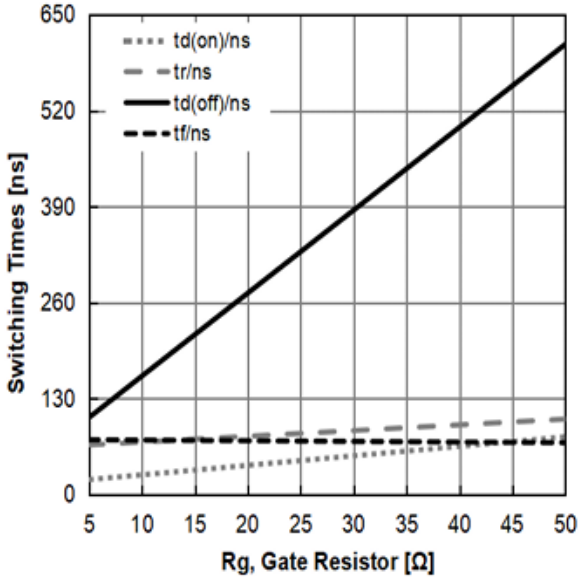


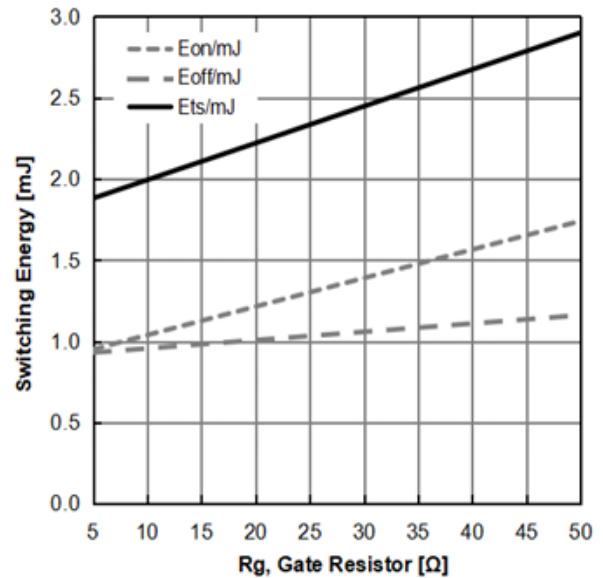
Figure 8: Typical Gate-Emitter Threshold Voltage vs. Junction Temperature



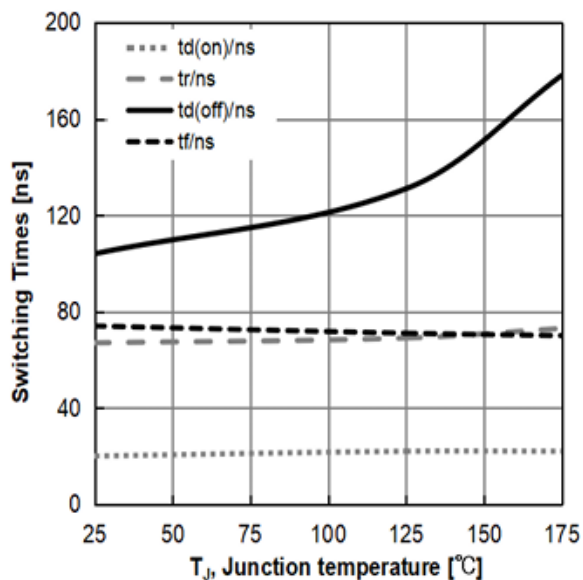
**Figure 9: Typical Switching Times vs. Gate Resistor ( $T_J=25^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=40\text{A}$ )**



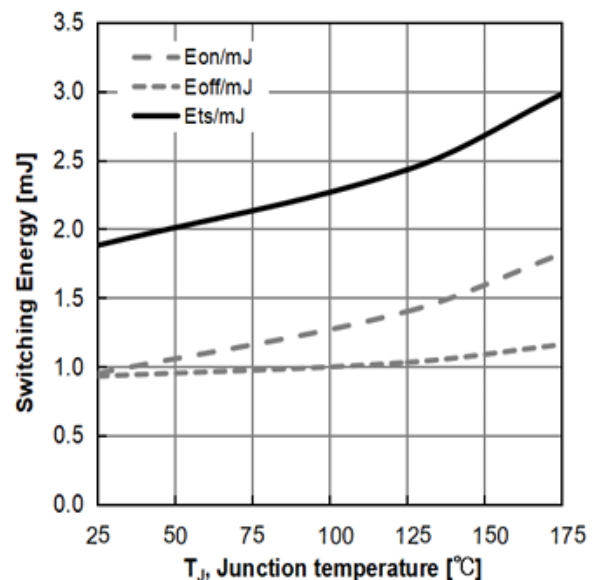
**Figure 10: Typical Switching Energy vs. Gate Resistor ( $T_J=25^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=40\text{A}$ )**



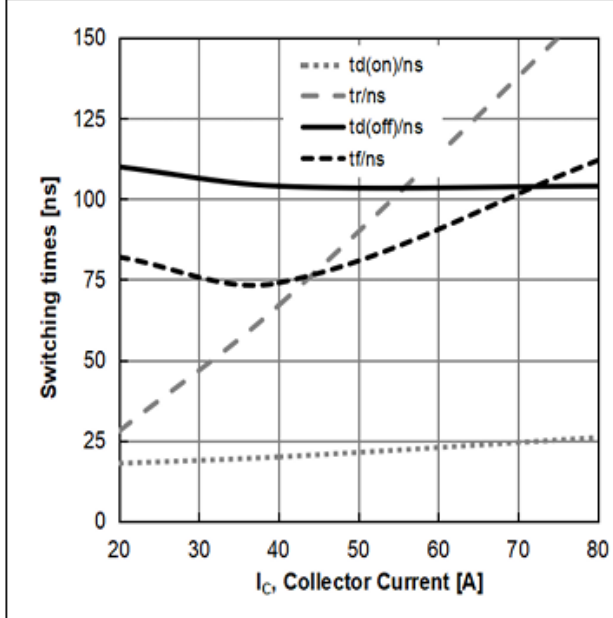
**Figure 11: Typical Switching Times vs. Junction Temperature ( $V_{CE}=400\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=40\text{A}$ ,  $R_g=5\Omega$ )**



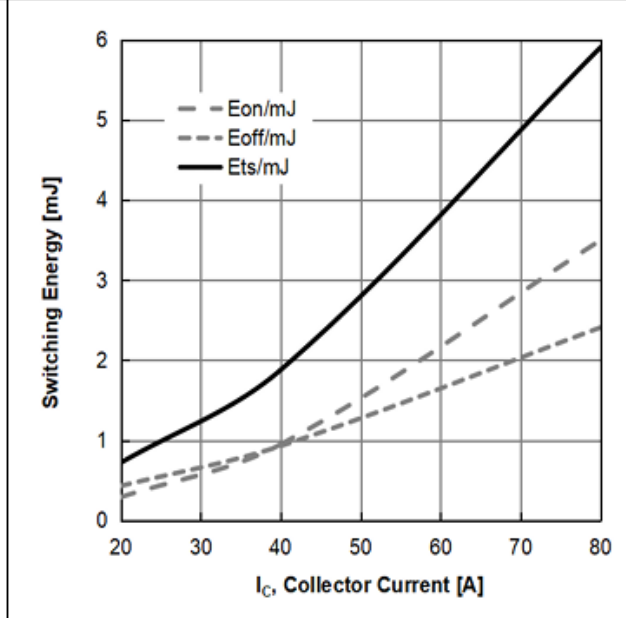
**Figure 12: Typical Switching Energy vs. Junction Temperature ( $V_{CE}=400\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=40\text{A}$ ,  $R_g=5\Omega$ )**



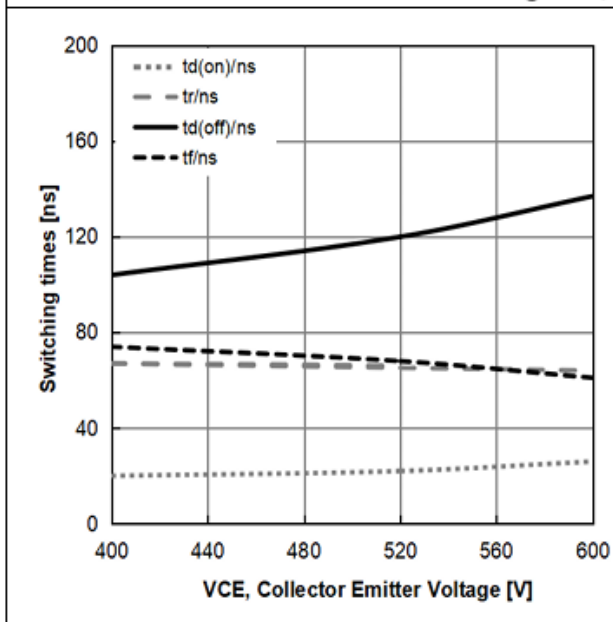
**Figure 13: Typical Switching Times vs. Collector Current ( $T_J=25^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_g=5\Omega$ )**



**Figure 14: Typical Switching Energy vs. Collector Current ( $T_J=25^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $V_{GE}=15\text{V}$ ,  $R_g=5\Omega$ )**



**Figure 15: Typical Switching Times vs. VCE ( $T_J=25^\circ\text{C}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=40\text{A}$ ,  $R_g=5\Omega$ )**



**Figure 16: Typical Switching Energy vs. VCE ( $T_J=25^\circ\text{C}$ ,  $V_{GE}=15\text{V}$ ,  $I_C=40\text{A}$ ,  $R_g=5\Omega$ )**

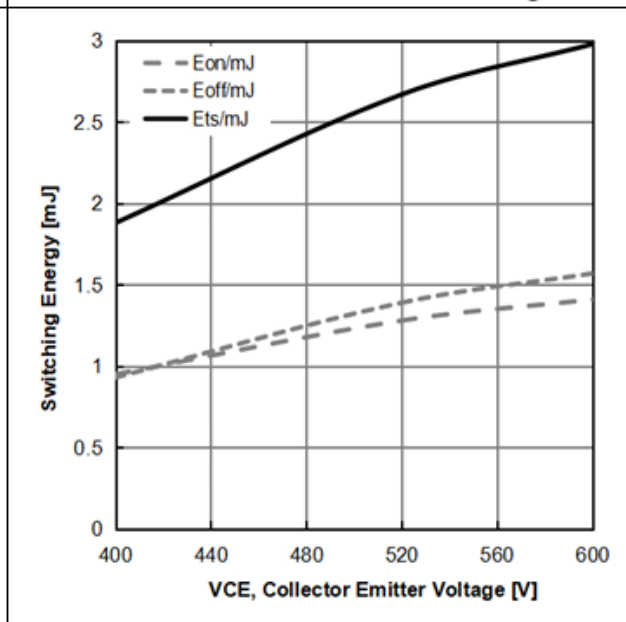


Figure 17: Typical Capacitance vs. Collector- Emitter Voltage

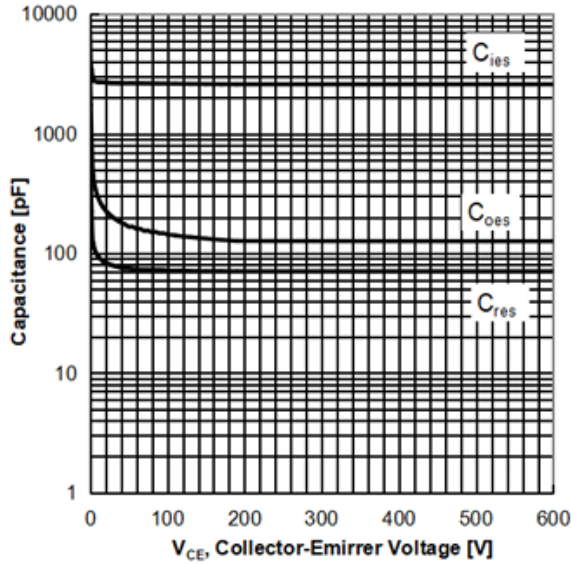


Figure 18: Typical Gate Charge

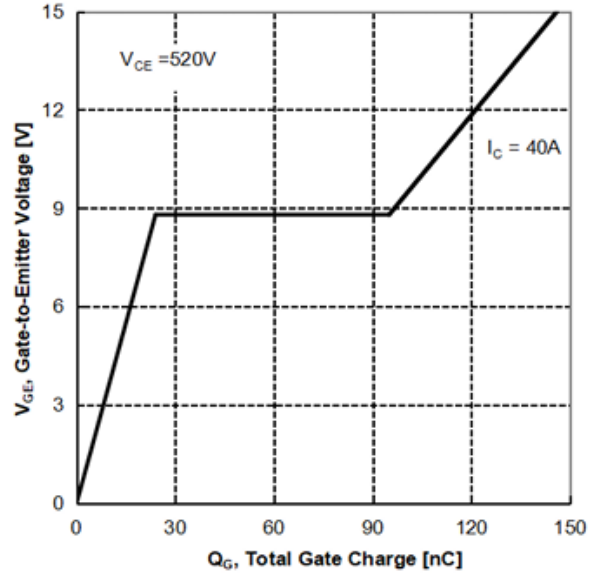


Figure 19: IGBT Transient Thermal Impedance vs. Pulse Width

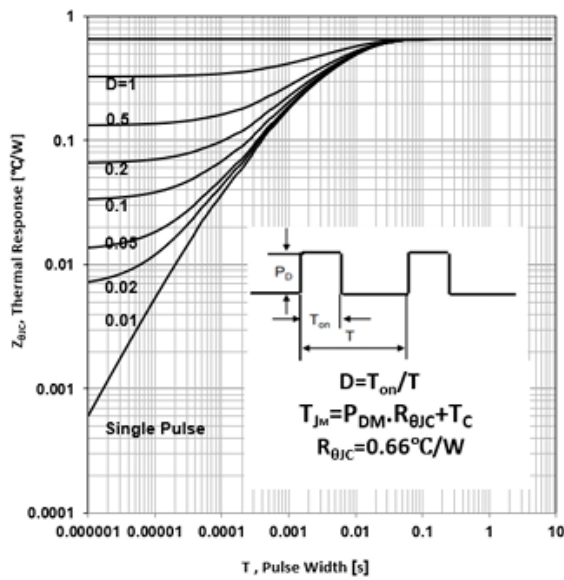


Figure 20: Diode Transient Thermal Impedance vs. Pulse Width

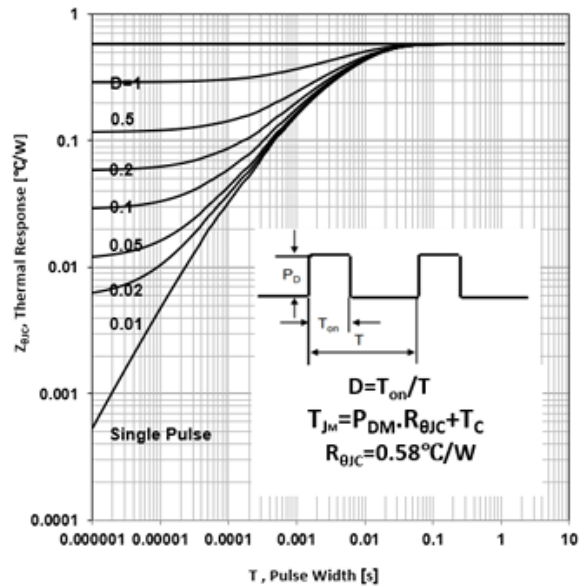
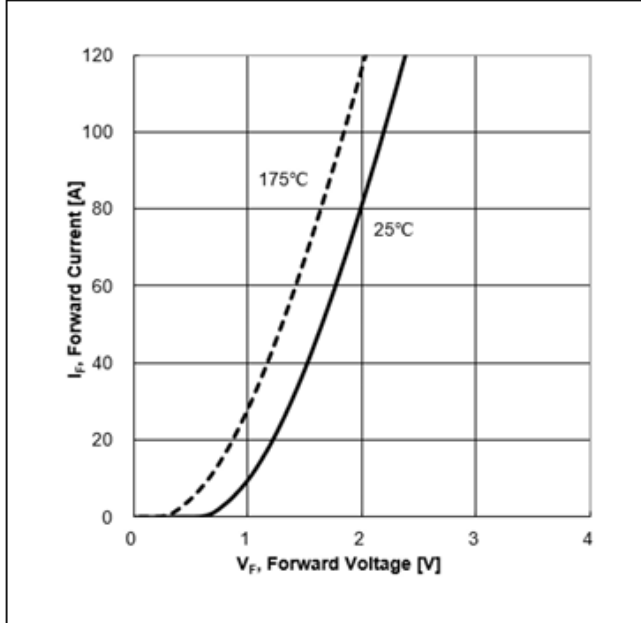
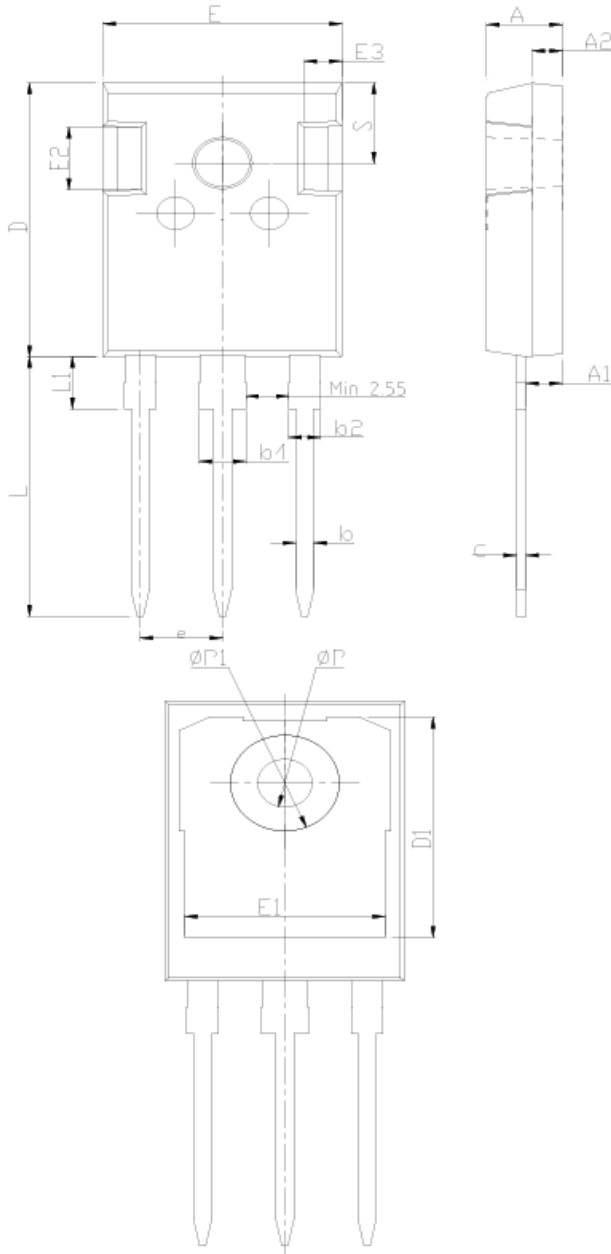


Figure 21: Typical Diode Forward Current vs. Forward Voltage





**TO-247 PACKAGE OUTLINE**



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.70	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44BSC		
L	19.62	19.92	20.22
L1	-	-	4.30
$\Phi P$	3.40	3.60	3.80
$\Phi P1$	-	-	7.30
S	6.15BSC		

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